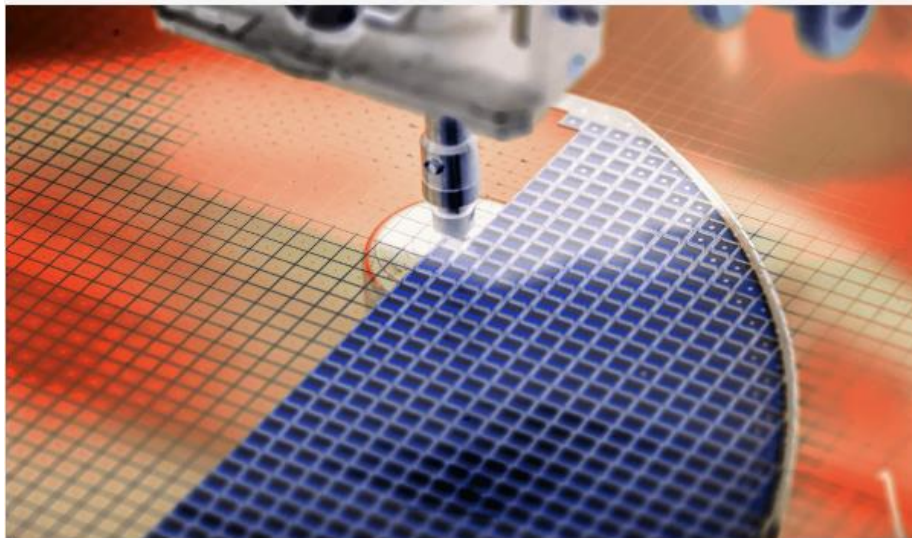




EV Group Completes Construction of New Manufacturing V Building at Corporate Headquarters to Expand Production Capacity– December 1, 2022



Flux-less TCB for Fine-Pitch Applications and Its Extension to Cu-Cu TCB

Typical interconnects are composed of solder-capped copper pillars, which exist either on a chip, on a substrate, or in some cases on both sides. The finest pitches in more recent advanced packaging applications range from 25 – 80 μ m and are implemented either through a conventional mass reflow (MR) or via a more sophisticated thermal compression bonding (TCB) process. The pitch and dimension scaling below 50 μ m, though very enticing, comes with challenges that cannot always be surmounted using traditional flux-based processes.

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[69th Annual IEEE International Electron Devices Meeting](#)
December 9-13, 2023

[SEMICON Japan 2023](#)
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December 7-10, 2024

